

Produktbeschreibung

BEST-Lötpaste (Zinnpaste) ist die beste Wahl für Reballing-ICs.

Original BEST Marke,

Qualität überprüft

Anwendung: kann für laptop / computer / handy / haushaltsgeräte SMD IC und BGA IC reparatur, werkzeuge für chip-ebenereparieren und Elektronikfertigungsline.

Technologieparameter

8
6
6
6
4
7
5

Z
e
g
h
e
ø
ø
%
g
s
u
b
b
m
e
n
s
ø
%
z
k
n
g
f
e
r
:
,
7
%

s
2
6
m
2
2
ø
ø
G
n
k
t
:

Z
B
n
A
p
u
u
m
e
r
p
a
r
t
i
k
e
l
g
r
ö
ß
e
:
Z
p
h
ä
p
ü
ß
a
b
r
f
o
r
m
e
n
:

Metabolism
of
the
cell
:
Käfer
Prä-
c
em-
p
e
r
a
t
u
r
:
Ng
W
S
t

SOLDER PASTE

Lead-free High temperature



500g

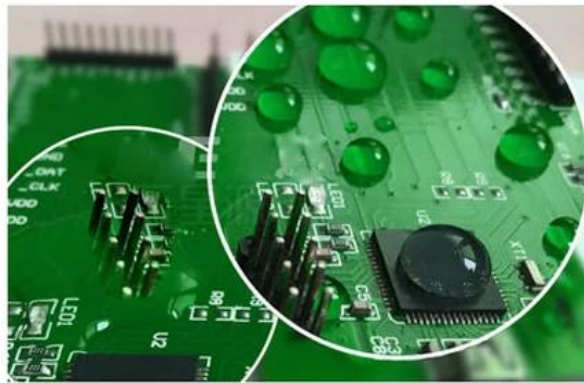
Low residue / Rapid welding / lead free / Solder spot bright / Ag

Product Usage

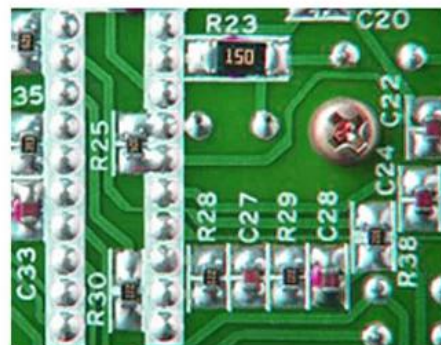
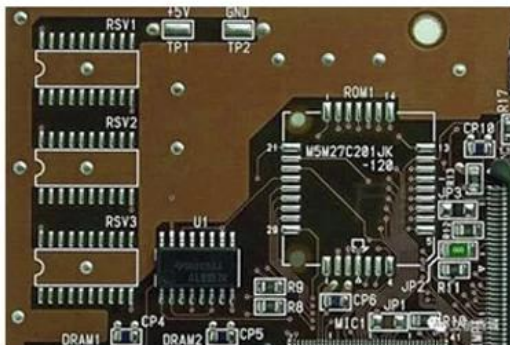


MODEL	BST-705
SHELF LIFE	6 months
INGREDIENT	Sn99/Ag0.3/Cu0.7
WEIGHT	500g
MELTING POINT	217°C

Having a large insulation resistance does not corrode the PCB, and the requirements for no-cleaning can be achieved.



High impedance, full and bright solder, low residue

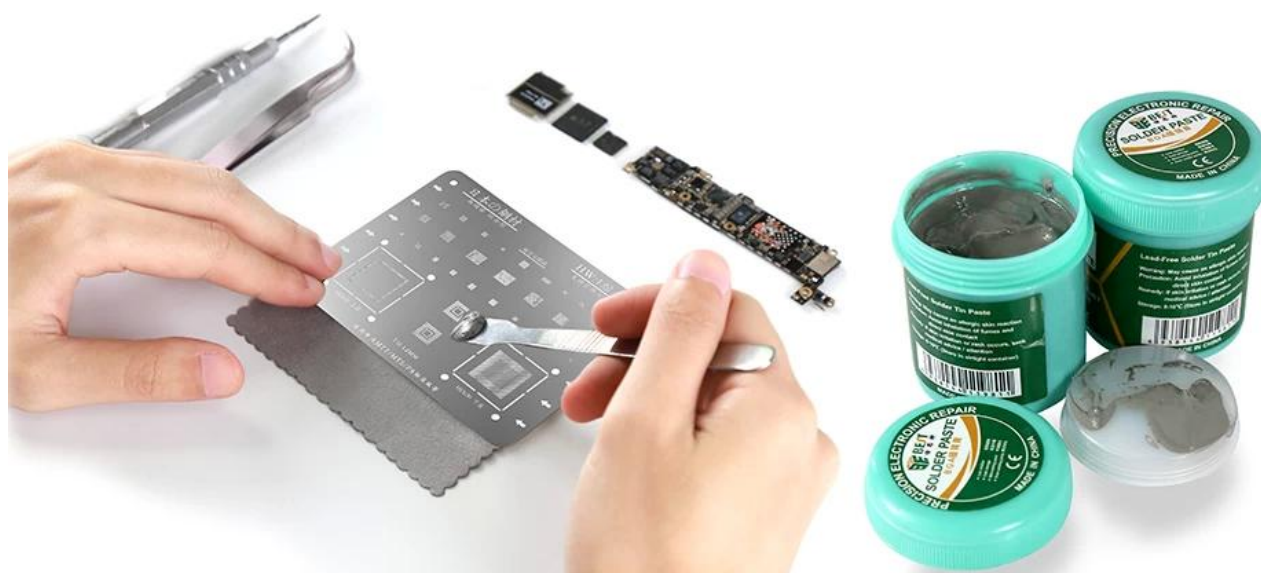


Welding requirements for a wide range of products



TESTING EFFECT

UNIFORM SOLDER JOINT
MEDIUM TEMPERATURE MELTING POINT



PRODUCT SIZE



63.0MM



52MM

75MM

